Control panel, 24 VDC, 7 Inches PCT-Display, 1024x600, 1xEthernet, 1xRS232, 1xRS485, 1xCAN, 1xProfibus, 1xSD card slot



Part no. XV-303-70-B02-A00-1B

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Product Sub Type Catalog Notes Cat	Certifications	EN 50178 DNV GL EMC according to 2014/30/EU CE UL File No.: E205091 UL UL 61010-2-201 CUL
Product Sub Type Catalog Notes Cat	Product Tradename	XV-303
Catalog Notes 11.9 W for basic device + 2.5 W for USB module Can be fitted by user with article no. 18558 LUF-PL-A Heat disapsion with power consumption for 24 V License certificates for onliband interfaces not required Optionally with 50 card > article no. 18638 LUF-PL-A Heat disapsion with power consumption for 24 V License certificates for onliband interfaces not required Optionally with 50 card > article no. 18638 LUF-PL-A Heat disapsion with power consumption for 24 V License certificates for onliband interfaces not required Optionally with 50 card > article no. 18638 LUF-PL-A LUF-PL-PL-PL-A LUF-PL-A LUF-PL-PL-PL-PL-PL-PL-PL-PL-PL-PL-PL-PL-PL-	Product Type	Touch panel
Enclosure material Enclosure Michael (built-in interface) I x USB device (built-in interface) I x USB device (built-in interface) I x USB device (built-in interface) I x CANopen®(seasyNet (built-in interface) I x CANopen®(seasyNet (built-in interface) I x CANopen®(seasyNet (built-in interface) I x USB host 20 (built-in interfa	Product Sub Type	None
Features Section	Catalog Notes	Can be fitted by user with article no. 181585 LIC-PLC-A Heat dissipation with power consumption for 24 V License certificates for onboard interfaces not required
Features Section		
CAN Integrated Runtime visualization software license RS22 Target and web visualization RS485 Ethernet interface Portrait format Stot for SD card Operating System Windows Embedded Compact 7 pro Fanless CPU and system cooling, natural convection-based passive cooling USB Host USB Host Interface In x USB device (built-in interface) 1 x USB host 2.0		
1 x USB device (built-in interface) 1 x RS232 (built-in interface) 1 x RS232 (built-in interface) Ressage indication 1 x Ethernet 10/100 Mbps (built-in interfaces) 1 x CANopen®/easyNet (built-in interfaces) 1 x CANopen®/easyNet (built-in interfaces) NPI interface Color display Message system (incl. buffer and confirmation) 1 x USB host 2.0 (built-in interface) 1 x RS485 (built-in interface) 1 x RS485 (built-in interface) Recipes Printer output SW interfaces Functions	Features	CAN Integrated Runtime visualization software license RS232 Target and web visualization RS485 Ethernet interface Portrait format Slot for SD card Operating System Windows Embedded Compact 7 pro Fanless CPU and system cooling, natural convection-based passive cooling
Additional software components, loadable Process default value (input) possible Battery runtime Back-up of real-time clock: BR 2330, non-replaceable (soldered) Degree of protection NEMA 4X NEMA 12 IP20, rear (according to EN 60529-1) Degree of protection (front side) IP65 NEMA 12	Fitted with:	1 x USB device (built-in interface) 1 x RS232 (built-in interface) Message indication 1 x Ethernet 10/100 Mbps (built-in interfaces) 1 x CANopen®/easyNet (built-in interfaces) MPI interface Color display Message system (incl. buffer and confirmation) 1 x USB host 2.0 (built-in interface) 1 x RS485 (built-in interface) Recipes Printer output
Degree of protection NEMA 4X NEMA 12 IP20, rear (according to EN 60529-1) Degree of protection (front side) IP65 NEMA 12	Functions	Additional software components, loadable
NEMA 12 IP20, rear (according to EN 60529-1) Degree of protection (front side) IP65 NEMA 12	Battery runtime	Back-up of real-time clock: BR 2330, non-replaceable (soldered)
NEMA 12	Degree of protection	NEMA 12
Fuse type Built-in fuse (not accessible)	Degree of protection (front side)	
	Fuse type	Built-in fuse (not accessible)

Lifespan	50,000 h (Service life of back-lighting)
Model	Plastic enclosure and glass panel in plastic frame
Mounting method	Flush mounting - Clearance: Width x Height x Depth ≥ 30 mm (1.18") Flush mounting - Inclination from vertical: ±45° (if using natural convection) Flush mounting
Potential isolation	Power supply: no
Protection against polarity reversal	Yes, for supply voltage (Siemens MPI optional)
Product category	HMI-PLC (SPS function, retrofittable)
RoHs conformity	Yes
Software	XSOFT-CODESYS-2, PLC-Programming software, Engineering GALILEO, Visualisation software, Engineering XSOFT-CODESYS-3, PLC-Programming software, Engineering XSOFT-CODESYS, Visualisation software, Engineering
Туре	Control panel with Profibus
Voltage type	DC
Shock resistance	15 g, 11 ms, Mechanical
Vibration resistance	5 - 9 Hz, ± 3.5 mm 60 - 150 Hz, ± 2 g 9 - 60 Hz, ± 0.15 mm
Air pressure	795 - 1080 hPa (operation)
Ambient operating temperature - min	0°C
Ambient operating temperature - max	50 °C
Ambient storage temperature - min	-20 °C
Ambient storage temperature - max	00 °C
Climatic proofing	Damp heat, constant, to IEC 60068-2-3 Cold to EN 60068-2-1 Dry heat to IEC 60068-2-2
Environmental conditions	Condensation: Non-condensing
Operating temperature - min	0 °C
Operating temperature - max	50 °C
Relative humidity	10 - 95 % (non-condensing)
Emitted interference	According to IEC/EN 61000-6-4
Interference immunity	According to EN 61000-6-2
Voltage dips	5 ms from undervoltage (19.2 V DC) ≤ 10 ms from rated voltage (24 V DC)
Permissible voltage	35 V DC (for a duration of < 100 ms) 18.0 - 31.2 V DC, absolute with ripple 18 - 31.2 V DC, battery powered (rated operating voltage -25 %/+30 %) 19.2 - 30 V DC, effective (rated operating voltage -20 %/+25 %)
Power consumption	14 W typ. Max. 14.4 W
Rated operational voltage	24 V DC (power-supply - safety extra low voltage)
Supply voltage at AC, 50 Hz - min	0 V AC
Supply voltage at AC, 50 Hz - max	0 V AC
Supply voltage at DC - min	19.2 V DC
Supply voltage at DC - max	30 V DC
Communication interface	PROFIBUS-DP, not galvanically isolated, 9 pole SUB-D socket, UNC
Interfaces	USB 2.0 device (not galvanically isolated) USB 2.0 host (not galvanically isolated) RS232 (not galvanically isolated, 9-pin SUB-D plug, UNC) 10/100 Mbps Ethernet connection CAN (not galvanically isolated, 9-pin SUB-D plug, UNC) RS485 (not galvanically isolated, 9-pin SUB-D plug, UNC)
Number of slots	1 (for SD-Card)
Protocol	TCP/IP EtherNet/IP MODBUS CAN PROFIBUS

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LED 1528 x 30 mm		
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Number of colors of the display	Display type	Color display, TFT, anti-glare
Resolution Screen size (diagonal) Touch technology Relative touch growth and touch pound touch panel touch sensor Capacitive multitouch Projected Capacitive multitouch Remany Remany capacity NRMA 17 Sahyen Remail School Stiff (sectoral memony) RAMA 57 Sahyen Remail School Stiff (sectoral memony) RAMA 57 Sahyen Remail School Stiff (sectoral memony) RAMA 57 Sahyen Remail	Luminance intensity	400 cd/m ²
Screen size (diagonal) Fouch inchinology South inchinology Multi-fouch touch panel fouch sensor Capacitive methods: Proportion of the fouch (PCT) Proportion of the fouch (PCT) Backup since To years, typ. (time at zero vallage) Memory Streat, type. SSIRS, SUMC (external memory) Streat, type. SSIRS, SUMC (external memory) DRAMA: STA Ways. RAMA Fast; 10 Eyes SLC Departing system Windows Embedded Compact 7 Pro ARM Cortex-A9 900 MHz Equipment heat dissipation, current-dependent Pvid 14.4 W Heat dissipation expectly Pfass OW Heat dissipation expectly Pfass Heat dissipation current for specified heat dissipation (In) Static heat dissipation, one-current-dependent Pvid Windows Embedded Compact 7 Pro ARM Cortex-A9 900 MHz Equipment heat dissipation, current-dependent Pvid 14.4 W 10.2.2 Corressor resistance Meets the product standard's requirements. 10.2.3.1 Verification of thermal stability of enclosure Meets the product standard's requirements. 10.2.3 Persist of insul, must to alternal spatiality by internal elect effects Meets the product standard's requirements. 10.2.3 Resistance to ultra-violet (UV) radiation Does not apply, since the entire switchgear needs to be evaluated. 10.2.5 Mechanical impact Does not apply, since the entire switchgear needs to be evaluated. 10.2.6 Mechanical impact Does not apply, since the entire switchgear needs to be evaluated. 10.2.6 Department of switching devices and components Meets the product standard's requirements. Meets the product standard's requirements. 10.2 Degree of protection of assemblies Meets the product standard's requirements. Meets the product standard's requirements. 10.2 Degree of protection of assemblies Meets the product standard's requirements. 10.3 Degree of protection of switchingear needs to be evaluated. Does not apply, since the entire switchgear needs to be evaluated. Does not apply, since the entire switchgear needs to be evaluated. 10.4 Clearances and crepage distances Meets the product standard's requirement	Number of colors of the display	16777216
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Backup time Memory Memory Memory Memory Departing system Mindows Embedded Compact 7 Pro ARM Corex- A9 800 MHz Equipment heat dissipation, current-dependent Prid Equipment heat dissipation, current-dependent Prid Hat dissipation capacity Priss Read operations current dependent Prid Met dissipation of pen pole, current-dependent Prid Hat dissipation of pen pole, current-dependent Prid NSTALL 18 W Heat dissipation of pen pole, current-dependent Prid I A4 W Hat dissipation of pen pole, current-dependent Prid NSTALL 18 W Hat dissipation of resistance of insulating materials to normal heat 10.2.3 I Verification of thermal stability of enclosures Meets the product standard's requirements. 10.2.3 Verification of thermal stability of enclosures Meets the product standard's requirements. 10.2.3 Peristrication of thermal stability of enclosures Meets the product standard's requirements. 10.2.3 Peristrication of thermal stability of enclosures Meets the product standard's requirements. 10.2.3 Peristrication of thermal stability of enclosures Meets the product standard's requirements. 10.2.3 Peristrication of thermal stability of enclosures Meets the product standard's requirements. 10.2.3 Peristrication of thermal stability of enclosures Meets the product standard's requirements. 10.2.3 Peristrication of ensistance of insulating materials to normal heat 10.2.3 Resistance to ultra-violet (IV/) radiation 10.2.4 Resistance to ultra-violet (IV/) radiation 10.3 Degree of protection of assemblies Meets the product standard's requirements. Meets the product standard's requirements. Meets the product standard's requirements. 10.3 Degree of protection of assemblies Meets the product standard's requirements. 10.5 Protection against electric shock Does not apply, since the entric switchgear needs to be evaluated. Des not apply, since the entric switchgear needs to be evaluated. 10.5 Incorporation of evitching devices and components 10.6 Encorporation of evitching devices and components	Screen size (diagonal)	7 in
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10.2.4 Resistance to ultra-violet (UV) radiation Please enquire Does not apply, since the entire switchgear needs to be evaluated. 10.2.6 Mechanical impact Does not apply, since the entire switchgear needs to be evaluated. 10.2.7 Inscriptions Meets the product standard's requirements. 10.4 Clearances and creepage distances Meets the product standard's requirements. 10.5 Protection against electric shock Does not apply, since the entire switchgear needs to be evaluated. 10.6 Incorporation of switching devices and components Does not apply, since the entire switchgear needs to be evaluated. 10.7 Internal electrical circuits and connections Is the panel builder's responsibility. 10.8 Connections for external conductors Is the panel builder's responsibility. 10.9.2 Power-frequency electric strength Is the panel builder's responsibility. 10.9.3 Impulse withstand voltage Is the panel builder's responsibility. 10.9.4 Testing of enclosures made of insulating material Is the panel builder is responsibility. 10.10 Temperature rise The panel builder is responsibility. 10.11 Short-circuit rating Is the panel builder's responsibility. 10.12 Electromagnetic compatibility Is the panel builder's responsibility. 10.13 Mechanical function The device meets the requirements, provided the information in the instruction	10.2.3.2 Verification of resistance of insulating materials to normal heat	Meets the product standard's requirements.
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10.13 Mechanical function The device meets the requirements, provided the information in the instruction	10.11 Short-circuit rating	Is the panel builder's responsibility.
	10.12 Electromagnetic compatibility	Is the panel builder's responsibility.
	10.13 Mechanical function	

Technical data ETIM 8.0

Programmable logic controllers PLC (EG000024) / Graphic panel (EC001412)			
Electric engineering, automation, process control engineering / Display and control component / Panel (HMI) / Graphic panel (HMI) (ecl@ss10.0.1-27-33-02-01 [AFX016003])			
Supply voltage AC 50 Hz	V	0 - 0	
Supply voltage AC 60 Hz	V	0 - 0	

Supply voltage DC	,	V	19.2 - 30
		V	DC
Voltage type of supply voltage			
Number of HW-interfaces industrial Ethernet			1
Number of interfaces PROFINET			0
Number of HW-interfaces RS-232			1
Number of HW-interfaces RS-422			0
Number of HW-interfaces RS-485			1
Number of HW-interfaces serial TTY			0
Number of HW-interfaces USB			2
Number of HW-interfaces parallel			0
Number of HW-interfaces Wireless			0
Number of HW-interfaces other			2
With SW interfaces			Yes
Supporting protocol for TCP/IP			Yes
Supporting protocol for PROFIBUS			Yes
Supporting protocol for CAN			Yes
Supporting protocol for INTERBUS			No
Supporting protocol for ASI			No
Supporting protocol for KNX			No
Supporting protocol for Modbus			Yes
Supporting protocol for Data-Highway			No
Supporting protocol for DeviceNet			No
Supporting protocol for SUCONET			No
Supporting protocol for LON			No
Supporting protocol for PROFINET IO			No
Supporting protocol for PROFINET CBA			No
Supporting protocol for SERCOS			No
Supporting protocol for Foundation Fieldbus			No
Supporting protocol for EtherNet/IP			Yes
Supporting protocol for AS-Interface Safety at Work			No
Supporting protocol for DeviceNet Safety			No
Supporting protocol for INTERBUS-Safety			No
Supporting protocol for PROFIsafe			No
Supporting protocol for SafetyBUS p			No
Supporting protocol for other bus systems			No
Radio standard Bluetooth			No
Radio standard Wi-Fi 802.11			No
Radio standard GPRS			No
Radio standard GSM			No No
Radio standard UMTS			No No
10 link master			
			No TET
Type of display			TFT
With colour display			Yes
Number of colours of the display			16,777,216
Number of grey-scales/blue-scales of display		. ,	0
Screen diagonal		inch	7
Number of pixels, horizontal			1,024
Number of pixels, vertical		. 5	600
Useful project memory/user memory		kByte	512,000
With numeric keyboard			No
With alpha numeric keyboard			No
Number of function buttons, programmable			0
Number of buttons with LED			0
Number of system buttons			1
Touch technology			Capacitive multitouch

With message indication		Yes
With message system (incl. buffer and confirmation)		Yes
Process value representation (output) possible		Yes
Process default value (input) possible		Yes
With recipes		Yes
Number of password levels		200
With printer output		Yes
Number of online languages		100
Additional software components, loadable		Yes
Degree of protection (IP), front side		IP65
Degree of protection (NEMA), front side		12
Operating temperature	°C	0 - 50
Rail mounting possible		No
Wall mounting/direct mounting		No
Suitable for safety functions		No
Width of the front	mm	196
Height of the front	mm	135
Built-in depth	mm	43.1